| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|----------|--------|---|---|---------------------|---------|------------------|
| L14 | 9 | ("5545466").URPN. | USPAT | OR | ON | 2006/08/15 15:51 |
| L15 | 2 | "20020137256".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR . | ON | 2006/08/15 16:36 |
| L16 | 13265 | (dielectric near "2" substrate PCB printed near2 circuit wiring near3 board) same foil with laminat\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:36 |
| L17 | 6421 | (dielectric near3 substrate PCB printed near2 circuit wiring near3 board) same foil with laminat\$3 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:36 |
| L18 | 189001 | "438"/\$.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:36 |
| L19 | 358719 | "257"/\$.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:36 |
| L20 | 104529 | "174"/\$.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:36 |
| L21 | 122 | L17 and L18 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L22 | 65 | L17 and L18 | USPAT | OR | ON | 2006/08/15 16:37 |
| L23 | 23 | ("4151543" "4376287" "4628598" "5278429" "5362926" "5545589" "5741575" "5949655").PN. OR ("6204454").URPN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/15 16:37 |
| L24 | 429 | foil near2 roughness | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/15 16:37 |

| L25 | 16 | L24 and L18 | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/15 16:37 |
|-----|-----|---|---|----|----|------------------|
| L26 | 29 | L24 and L19 | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/15 16:37 |
| L27 | 29 | L24 and L26 | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/15 16:37 |
| L28 | 1 | "6476331".pn. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/08/15 16:37 |
| L29 | 199 | foil with (smooth small) with roughness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L30 | 199 | foil with (smooth small) with roughness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L31 | 140 | foil with matte with roughness | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L32 | 99 | foil with matte with roughness | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L33 | 104 | foil with (smooth shiny) with roughness | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L34 | 104 | foil with (smooth shiny) with roughness | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L35 | 99 | foil with matte with roughness | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L36 | 78 | foil with matte with roughness | USPAT | OR | ON | 2006/08/15 16:37 |
| L37 | 78 | L36 and roughness | USPAT | OR | ON | 2006/08/15 16:37 |

| L38 | 99 | foil with matte with roughness | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
|-----|----|---|---|----|----|------------------|
| L39 | 38 | foil with matte with roughness same laminat\$5 | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L40 | 1 | jp-03269238-\$.did. | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L41 | 2 | jp-03296238-\$.did. | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L42 | 5 | foil with tooth with roughness | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L43 | 2 | "6893743".pn. | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L44 | 1 | "6893743".pn. and thick\$4 | USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L45 | 2 | "6,441,487".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L46 | 14 | ("4478883" "4997516" "5215645" "5 551627" "5834140" "5962133" "629 1081").PN. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:37 |
| L47 | 2 | "6,097,087".pn. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2006/08/15 16:50 |

| L48 | 55599 | (conductive metal) and (foil layer film) and rough\$5 | US-PGPUB | OR | ON | 2006/08/15 17:42 |
|-----|-------|---|----------|----|----|------------------|
| L49 | 54 | ((IC electronic semiconductor integrated adj circuit silicon) and package and (conductive metal) and (foil layer film) and rough\$5). clm. | US-PGPUB | OR | ON | 2006/08/15 17:43 |
| L50 | 1085 | ((IC electronic semiconductor integrated adj circuit silicon) and (conductive metal) and (foil layer film) and rough\$5).clm. | US-PGPUB | OR | ON | 2006/08/15 17:43 |
| L51 | 57 | ((IC electronic semiconductor integrated adj circuit silicon) and (package bga ball near2 grid) and (conductive metal) and (foil layer film) and rough\$5).clm. | US-PGPUB | OR | ON | 2006/08/15 17:43 |